
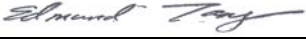





Initial Final

Contact Date:	Implementation Date:	Alert Category:	Alert Type:	PCN #:
August 24, 2009	November 22, 2009	Discrete Semiconductors	Change of Die Attach Method	PCN #: 1150 REV 00
TITLE				
Change of Die Attach Method from Eutectic to Soft Solder.				
IMPACT				
None.				
DESCRIPTION OF CHANGE				
This PCN is to notify customers of the qualification of soft solder die attach material in order to improve overall package performance. Affected products are listed below. Full electrical characterization and high reliability testing has been completed on representative devices assembled with the soft solder die attach material in order to ensure no change to device functionality or data sheet electrical specifications before shipment to our customers.				
PRODUCTS AFFECTED				
ZXMHC10A07T8TA ZXMHC3A01T8TA ZXMHC6A07T8TA ZXMHN6A07T8TA				
WEB LINKS				
Manufacturer's Notice:	http://www.diodes.com/quality/pcns/			
For More Information Contact:	http://www.diodes.com/contacts/			
Data Sheet:	http://www.diodes.com			
DISCLAIMER				
Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.				
PCN APPROVAL				
Signatories	Name	Signature	Date	
Signature of Sr. Vice President, Sales & Mktg.	Mark King		August 24, 2009	
Signature of VP Corporate Administration	Ed Tang		August 24, 2009	
Signature of VP Product Development	Francis Tang		August 24, 2009	
European President & VP Sales and Mktg.	Colin Greene		August 24, 2009	
European Sales Manager	Oliver Woyke		August 19, 2009	
VP Business Development	Jon Shilito	(approval on file)	August 19, 2009	